



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VN7016AJTR	RRTI*XV08AFS	A	64BA	2017-04-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	123.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	3.9-4.9-1.55	NA	flat	
Comment	POWERSO-16			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	die backside metal	195
Lead	3.78	soft solder	30707

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	RRT1*KV08AFS					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.163	mg	supplier	die	Silicon (Si)	7440-21-3		4.048	mg	972376	32911
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	1441	49
				supplier	Passivation	Silicon Nitride	12033-89-5		0.015	mg	3603	122
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	3843	130
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	480	16
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1441	49
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	5767	195
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	480	16
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.044	mg	10569	358
Leadframe	Copper & its alloys	56.687	mg	supplier	alloy	Copper (Cu)	7440-50-8		55.900	mg	986117	454472
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.056	mg	988	454
				supplier	metallization	Silver (Ag)	7440-22-4		0.731	mg	12895	5943
Soft solder	Solder	3.955	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.777	mg	954994	30707
				supplier	solder	Silver (Ag)	7440-22-4		0.099	mg	25031	805
				supplier	solder	Tin (Sn)	7440-31-5		0.079	mg	19975	642
Bonding wires	Other inorganic materials	0.523	mg	supplier	wire	Copper (Cu)	7440-50-8		0.523	mg	1000000	4252
				supplier	wire	Copper (Cu)	7440-50-8		0.523	mg	1000000	4252
Encapsulation	Other Organic Materials	57.672	mg	supplier	mold compound	Silica, vitreous	60676-86-0		49.829	mg	864007	405114
				supplier	mold compound	Epoxy Resin	25068-38-6		4.325	mg	74993	35163
				supplier	mold compound	Phenol Resin	29690-82-2		2.884	mg	50007	23447
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.288	mg	4993	2341
				supplier	mold compound	Quartz	14808-60-7		0.173	mg	3000	1407
				supplier	mold compound	Carbon black	1333-86-4		0.173	mg	3000	1407